

Appl. No. 10/711,617
Reply to Office action of November 29, 2007

REMARKS/ARGUMENTS

Request for Continued Examination:

5 The applicant respectfully requests continued examination of the above-indicated application as per 37 CFR 1.114.

Rejection of claims 1, 3-5 and 13-21 under 35 U.S.C 103(a) as being unpatentable over Applicant's admitted prior art (APA), figures 1-2, in view of Sato, US 2006/0097380.

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Claim 1 of the present invention is amended to incorporate the limitation that the gate driver chip and the source driver chip are mounted directly on the glass substrate with an anisotropic conductive film or a non-conductive film. Claims 3-4 are canceled accordingly.

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Claim 13 is also amended to incorporate the limitation that the driver chip is mounted directly on the glass substrate with an anisotropic conductive film or a non-conductive film. Claims 14-15 are canceled accordingly.

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In contrast to the present invention of using an anisotropic conductive film or a non-conductive film to bond the driver chip and the glass substrate, the material used for bonding the IC chip 9 and the circuit board 3 in Fig. 9 of the cited reference is an underfill layer 51. As the target substrate (such as a glass substrate) used for supporting the driver chip in the present invention is different from the substrate (such

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as a circuit board) of the cited reference, and the adhesive (such as an anisotropic conductive film or a non-conductive film) used for bonding the driver chip and the substrate is different from the adhesive (underfill material) of the cited reference, applicant asserts that the liquid crystal display module of the present invention is distinct from the one taught in the cited reference. The thickness of the driver chip

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(even if its less than 0.3 mm) disclosed in the cited reference thus cannot be applied to

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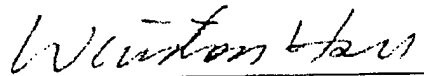
the liquid crystal display module of the present invention.

As the feature of using anisotropic conductive film or non-conductive film to bond the driver chip and the glass substrate is absent in Sato's invention, applicant
5 asserts that the admitted prior art of the present invention and Sato's invention cannot be combined in the manner suggested. Reconsideration of the amended claims 1 and 13 is respectfully requested. As claims 5 and 16-21 are dependent upon claims 1 and 13, applicant asserts that if claims 1 and 13 are found allowable, claims 5 and 16-21 should additionally be found allowable.

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Applicant respectfully requests that a timely Notice of Allowance be issued in this case.

15 Sincerely yours,



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Winston Hsu, Patent Agent No. 41,526
P.O. BOX 506, Merrifield, VA 22116, U.S.A.
20 Voice Mail: 302-729-1562
Facsimile: 806-498-6673
e-mail : winstonhsu@naipo.com

Note: Please leave a message in my voice mail if you need to talk to me. (The time in
25 D.C. is 13 hours behind the Taiwan time, i.e. 9 AM in D.C. = 10 PM in Taiwan.)